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Method and device for conditioning semiconductor wafers and/or hybrids

ABSTRACT

The present invention provides a method for conditioning semiconductor wafers and/or hybrids having the steps: preparation of a space (1) which is at least partially enclosed and has a wafer/hybrid holding device (10) which is located therein and has the purpose of holding a semiconductor wafer and/or hybrid; and conduction of a dry fluid through the wafer/hybrid holding device (10) in order to heat-treat the wafer/hybrid holding device (10); wherein at least a portion of the fluid leaving the wafer/hybrid holding device (10) is used to condition the atmosphere within the space (1). The invention also provides a corresponding device for conditioning semiconductor wafers and/or hybrids.

(Fig. 1)

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